

Application Data Sheet

Application Information

Application number::

Filing Date::

Application Type:: Regular

Subject Matter:: Utility

Suggested classification::

Suggested Group Art Unit::

CD-ROM or CD-R??::

Number of CD disks::

Number of copies of CDs::

Sequence Submission::

Computer Readable Form (CRF)?::

Number of copies of CRF::

Title:: METHOD AND DEVICE FOR MANUFACTURING
BONDING PADS FOR CHIP SCALE
PACKAGING

Attorney Docket Number:: 021653-003100US

Request for Early Publication:: No

Request for Non-Publication:: No

Suggested Drawing Figure::

Total Drawing Sheets:: 3

Small Entity?:: No

Latin name::

Variety denomination name::

Petition included?:: No

Petition Type::

Licensed US Govt. Agency::

Contract or Grant Numbers One::

Secrecy Order in Parent Appl.: No

Applicant Information

Applicant Authority Type: Inventor

Primary Citizenship Country: Republic of China

Status: Full Capacity

Given Name: Yuan-Heng

Middle Name:

Family Name: Fan

Name Suffix:

City of Residence: Shanghai

State or Province of Residence:

Country of Residence: Peoples Republic of China

Street of Mailing Address: 18 Zhang Jiang Road

City of Mailing Address: Shanghai

State or Province of mailing address:

Country of mailing address: Peoples Republic of China

Postal or Zip Code of mailing address: 201203

Correspondence Information

Correspondence Customer Number: 20350

Representative Information

Representative Customer Number: 20350

Domestic Priority Information

Application: Continuity Type: Parent Application: Parent Filing Date:

Foreign Priority Information

Country::	Application number::	Filing Date::
People's Republic of China	200310122967.9	12/30/03

Assignee Information

Assignee Name:: Semiconductor Manufacturing International (Shanghai) Corporation
Street of mailing address:: 18 Zhang Jiang Road, Pudong New Area
City of mailing address:: Shanghai
State or Province of mailing address::
Country of mailing address:: People's Republic of China
Postal or Zip Code of mailing address:: 201203